### H05K PRINTED CIRCUITS; CASINGS OR CONSTRUCTIONAL DETAILS OF ELECTRIC APPARATUS; MANUFACTURE OF ASSEMBLAGES OF ELECTRICAL COMPONENTS

#### NOTES

1. This subclass covers:
   - combinations of a radio or television receiver with apparatus having a different main function;
   - printed circuits structurally associated with non-printed electric components.

2. In this subclass, the following expression is used with the meaning indicated:
   - "printed circuits" covers all kinds of mechanical constructions of circuits that consist of an insulating base or support carrying the conductor and are combined structurally with the conductor throughout their length, especially in a two-dimensional plane, the conductors of which are secured to the base in a non-dismountable manner, and also covers the processes or apparatus for manufacturing such constructions, e.g. forming the circuit by mechanical or chemical treatment of a conductive foil, paste, or film on an insulating support.

#### WARNING

In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

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H05K

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1/0242 . . . . [Structural details of individual signal conductors, e.g. related to the skin effect]
1/0243 . . . . [Printed circuits associated with mounted high frequency components]
1/0245 . . . . [Lay-out of balanced signal pairs, e.g. differential lines or twisted lines]
1/0246 . . . . [Termination of transmission lines]
1/0248 . . . . [Skew reduction or using delay lines]
1/025 . . . . . [Impedance arrangements, e.g. impedance matching, reduction of parasitic impedance (H05K 1/024 and H05K 1/0243 take precedence; for semiconductor devices H01L 23/661)]
1/0251 . . . . . (related to vias or transitions between vias and transmission lines)]
1/0253 . . . . . [Impedance adaptations of transmission lines by special lay-out of power planes, e.g. providing openings (H05K 1/0251 takes precedence)]
1/0254 . . . . . [High voltage adaptations; Electrical insulation details; Overvoltage or electrostatic discharge protection (electrostatic discharge protection for electric apparatus in general H05K 9/007; H05K 9/0079); Arrangements for regulating voltages or for using plural voltages]
1/0256 . . . . . [Electrical insulation details, e.g. around high voltage areas]
1/0257 . . . . . [Overvoltage protection]
1/0259 . . . . . [Electrostatic discharge [ESD] protection]
1/026 . . . . . . [Spark gaps]
1/0262 . . . . . [Arrangements for regulating voltages or for using plural voltages]
1/0263 . . . . . [High current adaptations, e.g. printed high current conductors or using auxiliary non-printed means; Fine and coarse circuit patterns on one circuit board (H05K 1/0293 takes precedence)]
1/0265 . . . . . [characterized by the lay-out of or details of the printed conductors, e.g. reinforced conductors, redundant conductors, conductors having different cross-sections]
1/0266 . . . . . [Marks, test patterns, inspection means or identification means]
1/0268 . . . . . [for electrical inspection or testing]
1/0269 . . . . . [for visual or optical inspection]
1/0271 . . . . . [Arrangements for reducing stress or warp in rigid printed circuit boards, e.g. caused by loads, vibrations or differences in thermal expansion]
1/0272 . . . . . [Adaptations for fluid transport, e.g. channels, holes]
1/0274 . . . . . [Optical details, e.g. printed circuits comprising integral optical means (H05K 1/0269 takes precedence; coupling light guides with optoelectronic components G02B 6/42)]
1/0275 . . . . . [Security details, e.g. tampering prevention or detection]
1/0277 . . . . . [Bendability or stretchability details (H05K 1/038; H05K 3/4691 take precedence)]
1/0278 . . . . . [Rigid circuit boards or rigid supports of circuit boards locally made bendable, e.g. by removal or replacement of material]
1/028 . . . . . [Bending or folding regions of flexible printed circuits (H05K 1/0283 takes precedence)]
1/0281 . . . . . [Reinforcement details thereof]
1/0283 . . . . . [Stretchable printed circuits]
1/0284 . . . . . [Details of three-dimensional rigid printed circuit boards (H05K 1/119 takes precedence; shaping of the substrate H05K 3/0014)]
1/0286 . . . . . [Programmable, customizable or modifiable circuits (by programmable non-printed jumper connections H05K 3/222)]
1/0287 . . . . . [having an universal lay-out, e.g. pad or land grid patterns or mesh patterns]
1/0289 . . . . . [having a matrix lay-out, i.e. having selectively interconnectable sets of X-conductors and Y-conductors in different planes]
1/029 . . . . . [having a programmable lay-out, i.e. adapted for choosing between a few possibilities]
1/0292 . . . . . [having a modifiable lay-out, i.e. adapted for engineering changes or repair (H05K 1/0293 takes precedence)]
1/0293 . . . . . [Individual printed conductors which are adapted for modification, e.g. fusible or breakable conductors, printed switches]
1/0295 . . . . . [adapted for choosing between different types or different locations of mounted components]
1/0296 . . . . . [Conductive pattern lay-out details not covered by sub groups H05K 1/02 - H05K 1/0295 (H05K 1/11 takes precedence; lay-out adapted to mounted component configuration H05K 1/18)]
1/0298 . . . . . [Multilayer circuits]
1/03 . . . . . . Use of materials for the substrate
1/0306 . . . . . . [Inorganic insulating substrates, e.g. ceramic, glass]
1/0313 . . . . . . [Organic insulating material]
1/032 . . . . . . [consisting of one material]

NOTE

In this group, in the absence of an indication to the contrary, a material is classified in the last appropriate place

1/0326 . . . . . . [containing O]
1/0333 . . . . . . [containing S]
1/034 . . . . . . [containing halogen]
1/0346 . . . . . . [containing N]
1/0353 . . . . . . [consisting of two or more materials, e.g. two or more polymers, polymer + filler, + reinforcement]
1/036 . . . . . . [Multilayers with layers of different types]
1/0366 . . . . . . [reinforced, e.g. by fibres, fabrics (H05K 1/026 takes precedence)]
1/0373 . . . . . . [containing additives, e.g. fillers (H05K 1/026 takes precedence)]
1/038 . . . . . . [Textiles (used as reinforcing materials for organic insulating substrates H05K 1/0366)]
1/0386 . . . . . . [Paper sheets (used as reinforcing materials for organic insulating substrates H05K 1/0366)]
1/0393 . . . . . . [Flexible materials (H05K 1/038 takes precedence; specific organic compositions are classified in H05K 1/0313 and subgroups)]
1/05 . . . . . . Insulated {conductive substrates, e.g. insulated} metal substrate
1/053 . . . [the metal substrate being covered by an inorganic insulating layer]
1/056 . . . [the metal substrate being covered by an organic insulating layer]
1/09 . . . Use of materials for the {conductive, e.g.} metallic pattern
1/092 . . . [Dispersed materials, e.g. conductive pastes or inks]
1/095 . . . [for polymer thick films, i.e. having a permanent organic polymeric binder]
1/097 . . . [Inks comprising nanoparticles, i.e. inks which are sinterable at low temperatures]
1/11 . . . Printed elements for providing electric connections to or between printed circuits
1/111 . . . [Pads for surface mounting, e.g. lay-out]
1/112 . . . [directly combined with via connections]
1/113 . . . [Via provided in pad; Pad over filled via]
1/114 . . . [Pad being close to via, but not surrounding the via]
1/115 . . . [Via connections; Lands around holes or via connections (H05K 1/112 takes precedence)]
1/116 . . . [Lands, clearance holes or other lay-out details concerning the surrounding of a via]
1/117 . . . [Pads along the edge of rigid circuit boards, e.g. for pluggable connectors]
1/118 . . . [specially for flexible printed circuits, e.g. using folded portions]
1/119 . . . [Details of rigid insulating substrates therefor, e.g. three-dimensional details (H05K 1/117 takes precedence)]
1/14 . . . Structural association of two or more printed circuits (providing electric connection to or between printed circuits H05K 1/11, H01R 12/00)
1/141 . . . [One or more single auxiliary printed circuits mounted on a main printed circuit, e.g. modules, adapters (H05K 1/142 and H05K 1/147 take precedence)]
1/142 . . . [Arrangements of planar printed circuit boards in the same plane, e.g. auxiliary printed circuit insert mounted in a main printed circuit]
1/144 . . . [Stacked arrangements of planar printed circuit boards]
1/145 . . . [Arrangements wherein electric components are disposed between and simultaneously connected to two planar printed circuit boards, e.g. Cordwood modules]
1/147 . . . [at least one of the printed circuits being bent or folded, e.g. by using a flexible printed circuit (H05K 1/148 takes precedence)]
1/148 . . . [Arrangements of two or more hingeably connected rigid printed circuit boards, i.e. connected by flexible means]
1/16 . . . incorporating printed electric components, e.g. printed resistor, capacitor, inductor
1/162 . . . [incorporating printed capacitors]
1/165 . . . [incorporating printed inductors]
1/167 . . . [incorporating printed resistors]
1/18 . . . Printed circuits structurally associated with non-printed electric components ([H05K 1/0201, H05K 1/023, H05K 1/0243, H05K 1/16 take precedence])
1/181 . . . [associated with surface mounted components]

1/182 . . . [associated with components mounted in the printed circuit board, e.g. IMC (insert mounted components)]
1/183 . . . [Components mounted in and supported by recessed areas of the printed circuit board]
1/184 . . . [Components including terminals inserted in holes through the printed circuit board and connected to printed contacts on the walls of the holes or at the edges thereof or protruding over or into the holes]
1/185 . . . [Components encapsulated in the insulating substrate of the printed circuit or incorporated in internal layers of a multilayer circuit (semiconductor chips encapsulated by interconnect and support structures H01L 23/5389, H01L 24/00)]
1/186 . . . [manufactured by mounting on or connecting to patterned circuits before or during embedding]
1/187 . . . [the patterned circuits being prefabricated circuits, which are not yet attached to a permanent insulating substrate, e.g. on a temporary carrier]
1/188 . . . [manufactured by mounting on or attaching to a structure having a conductive layer, e.g. a metal foil, such that the terminals of the component are connected to or adjacent to the conductive layer before embedding, and by using the conductive layer, which is patterned after embedding, at least partially for connecting the component]
1/189 . . . [characterised by the use of a flexible or folded printed circuit (H05K 3/326 takes precedence)]

3/00 Apparatus or processes for manufacturing printed circuits

3/0002 . . . [for manufacturing artworks for printed circuits]
3/0005 . . . [for designing circuits by computer]
3/0008 . . . [for aligning or positioning of tools relative to the circuit board (H05K 3/4638, H05K 3/4679 takes precedence; for manufacturing assemblies of components H05K 13/0015)]
3/0011 . . . [Working of insulating substrates or insulating layers]
3/0014 . . . [Shaping of the substrate, e.g. by moulding]
3/0017 . . . [Etching of the substrate by chemical or physical means]
3/002 . . . [by liquid chemical etching]
3/0023 . . . [by exposure and development of a photosensitive insulating layer]
3/0026 . . . [by laser ablation]
3/0029 . . . [of inorganic insulating material]
3/0032 . . . [of organic insulating material]
3/0035 . . . [of blind holes, i.e. having a metal layer at the bottom]
3/0038 . . . [combined with laser drilling through a metal layer]
3/0041 . . . [by plasma etching]
3/0044 . . . [Mechanical working of the substrate, e.g. drilling or punching (H05K 3/0008 takes precedence)]
3/0047 . . . [Drilling of holes]
3/005 . . . [Punching of holes]
3/0052 . . . [Depaneling, i.e. dividing a panel into circuit boards; Working of the edges of circuit boards]
H05K

3/0055 . . . . [After-treatment, e.g. cleaning or desmearing of holes]
3/0058 . . . . (Laminating printed circuit boards onto other substrates, e.g. metallic substrates (H05K 1/0281 takes precedence))
3/0061 . . . . [onto a metallic substrate, e.g. a heat sink (heat sinks for electric apparatus H05K 7/20)]
3/0064 . . . . [onto a polymeric substrate]
3/0067 . . . . [onto an inorganic, non-metallic substrate]
3/007 . . . . (Manufacture or processing of a substrate for a printed circuit board supported by a temporary or sacrificial carrier (H05K 1/187, H05K 3/20 and H05K 3/4682 take precedence))
3/0073 . . . . (Masks not provided for in groups H05K 3/02 - H05K 3/46, e.g. for photomechanical production of patterned surfaces)
3/0076 . . . . [characterised by the composition of the mask]
3/0079 . . . . [characterised by the method of application or removal of the mask (H05K 3/0091 takes precedence)]
3/0082 . . . . [characterised by the exposure method of radiation-sensitive masks]
3/0085 . . . . [Apparatus for treatments of printed circuits with liquids not provided for in groups H05K 3/02 - H05K 3/46; conveyors and holding means therefor (apparatus specially adapted for manufacturing assemblies of electric components, e.g. printed circuit boards, H05K 13/00)]
3/0088 . . . . [for treatment of holes]
3/0091 . . . . [Apparatus for coating printed circuits using liquid non-metallic coating compositions]
3/0094 . . . . [Filling or covering plated through-holes or blind plated vias, e.g. for masking or for mechanical reinforcement]
3/0097 . . . . [Processing two or more printed circuits simultaneously, e.g. made from a common substrate, or temporarily stacked circuit boards (H05K 3/0052 takes precedence)]
3/02 . . . . in which the conductive material is applied to the surface of the insulating support and is thereafter removed from such areas of the surface which are not intended for current conducting or shielding
3/022 . . . . [Processes for manufacturing precursors of printed circuits, i.e. copper-clad substrates]
3/025 . . . . [by transfer of thin metal foil formed on a temporary carrier, e.g. peel-apart copper]
3/027 . . . . [the conductive material being removed by irradiation, e.g. by photons, alpha or beta particles]
3/04 . . . . the conductive material being removed mechanically, e.g. by punching
3/041 . . . . [by using a die for cutting the conductive material]
3/043 . . . . [by using a moving tool for milling or cutting the conductive material]
3/045 . . . . [by making a conductive layer having a relief pattern, followed by abrading of the raised portions]
3/046 . . . . [by selective transfer or selective detachment of a conductive layer]
3/048 . . . . [using a lift-off resist pattern or a release layer pattern]
3/06 . . . . the conductive material being removed chemically or electrolytically, e.g. by photo-etch process (semi-additive methods H05K 3/108)]
3/061 . . . . [Etching masks]
3/062 . . . . [consisting of metals or alloys or metallic inorganic compounds (H05K 3/065 takes precedence)]
3/064 . . . . [Photoresists]
3/065 . . . . [applied by electrographic, electrophotographic or magnetographic methods]
3/067 . . . . [Etchants]
3/068 . . . . [Apparatus for etching printed circuits]
3/07 . . . . being removed electrolytically
3/08 . . . . the conductive material being removed by electric discharge, e.g. by spark erosion
3/10 . . . . in which conductive material is applied to the insulating support in such a manner as to form the desired conductive pattern
3/101 . . . . [by casting or moulding of conductive material]
3/102 . . . . [by bonding of conductive powder, i.e. metallic powder (H05K 3/12 takes precedence)]
3/103 . . . . [by bonding or embedding conductive wires or strips]
3/105 . . . . [by conversion of non-conductive material on or in the support into conductive material, e.g. by using an energy beam]
3/106 . . . . [by photographic methods]
3/107 . . . . [by filling grooves in the support with conductive material (H05K 3/045, H05K 3/101, H05K 3/128 and H05K 3/465 take precedence)]
3/108 . . . . [by semi-additive methods; masks therefor (characterised by metallic etch mask H05K 3/062; electroplating methods or apparatus H05K 3/241)]
3/12 . . . . using {thick film techniques, e.g.} printing techniques to apply the conductive material (or similar techniques for applying conductive paste or ink patterns)
3/1208 . . . . [Pretreatment of the circuit board, e.g. modifying wetting properties; Patterning by using affinity patterns (providing shape patterns H05K 3/1258; adhesion treatments H05K 3/38)]
3/1216 . . . . [by screen printing or stencil printing]
3/1225 . . . . . . . . [Screens or stencils; Holders therefor]
3/1233 . . . . [Methods or means for supplying the conductive material and for forcing it through the screen or stencil]
3/1241 . . . . [by ink-jet printing or drawing by dispensing]
3/125 . . . . . . . . [by ink-jet printing]
3/1258 . . . . [by using a substrate provided with a shape pattern, e.g. grooves, banks, resist pattern]
3/1266 . . . . [by electrographic or magnetographic printing]
3/1275 . . . . [by other printing techniques, e.g. letterpress printing, intaglio printing, lithographic printing, offset printing]
3/1283 . . . . [After-treatment of the printed patterns, e.g. sintering or curing methods]
3/1291 . . . . [Firing or sintering at relative high temperatures for patterns on inorganic boards, e.g. co-firing of circuits on green ceramic sheets]
3/14 . . . . using spraying techniques to apply the conductive material [, e.g. vapour evaporation]
3/143 . . . . [Masks therefor (H05K 3/048 takes precedence)]
3/146 . . . [By vapour deposition]
3/161 . . . by cathodic sputtering
3/18 . . . using precipitation techniques to apply the conductive material
3/181 . . . [by electroless plating (adhesives therefor H05K 3/387)]
3/182 . . . [characterised by the patterning method]
3/184 . . . . [using masks]
3/185 . . . . [by making a catalytic pattern by photo-imaging]
3/187 . . . . [means therefor, e.g. baths, apparatus]
3/188 . . . by direct electroplating
3/202 . . . [using self-supporting metal foil pattern]
3/205 . . . [using a pattern electroplated or electroformed on a metallic carrier]
3/207 . . . [using a prefabricated paste pattern, ink pattern or powder pattern]
3/22 . . . Secondary treatment of printed circuits (H05K 3/1283 takes precedence; embedding circuits in grooves by pressure H05K 3/107)
3/222 . . . [Completing of printed circuits by adding non-printed jumper connections (printed jumper connections H05K 3/4685)]
3/225 . . . [Correcting or repairing of printed circuits (H05K 1/0292, H05K 3/222, H05K 3/288, H05K 3/4685 take precedence)]
3/227 . . . [Drying of printed circuits]
3/24 . . . Reinforcing the conductive pattern [(by solder coating H05K 3/3457)]
3/241 . . . [characterised by the electroplating method; means therefor, e.g. baths or apparatus]
3/242 . . . [characterised by using temporary conductors on the printed circuit for electrically connecting areas which are to be electroplated]
3/243 . . . [characterised by selective plating, e.g. for finish plating of pads (selective plating for making the circuit pattern H05K 3/108, H05K 3/182)]
3/244 . . . [Finish plating of conductors, especially of copper conductors, e.g. for pads or lands (selective plating methods H05K 3/243; finish plating of conductors made by printing techniques H05K 3/246; solder as finish H05K 3/3457, e.g. by plating H05K 3/3473)]
3/245 . . . [Reinforcing conductive patterns made by printing techniques or by other techniques for applying conductive pastes, inks or powders; Reinforcing other conductive patterns by such techniques]
3/246 . . . [Reinforcing conductive paste, ink or powder patterns by other methods, e.g. by plating]
3/247 . . . [Finish coating of conductors by using conductive pastes, inks or powders]
3/248 . . . . [fired compositions for inorganic substrates]
3/249 . . . . [comprising carbon particles as main constituent]
3/26 . . . Cleaning or polishing of the conductive pattern
3/28 . . . Applying non-metallic protective coatings (H05K 3/0091 takes precedence; methods for intermediate insulating layers for build-up multilayer circuits H05K 3/4673)]
3/281 . . . . [by means of a preformed insulating foil (H05K 3/284 takes precedence)]
3/282 . . . . [for inhibiting the corrosion of the circuit, e.g. for preserving the solderability]
3/284 . . . . [for encapsulating the circuit (H05K 1/185 takes precedence)]
3/285 . . . . [Permanent coating compositions]
3/287 . . . . [Photosensitive compositions]
3/288 . . . . [Removal of non-metallic coatings, e.g. for repairing]
3/30 . . . Assembling printed circuits with electric components, e.g. with resistor
3/301 . . . [by means of a mounting structure (H05K 3/325 takes precedence)]
3/303 . . . [Surface mounted components, e.g. affixing before soldering, aligning means, spacing means (H05K 3/32 takes precedence)]
3/305 . . . . [Affixing by adhesive]
3/306 . . . . [Lead-in-hole components, e.g. affixing or retention before soldering, spacing means (H05K 3/32 takes precedence)]
3/308 . . . . [Adaptations of leads (connectors to printed circuits H01R 12/00)]
3/32 . . . electrically connecting electric components or wires to printed circuits
3/321 . . . . [by conductive adhesives]
3/323 . . . . [by applying an anisotropic conductive adhesive layer over an array of pads]
3/325 . . . . [by abutting or pinching, i.e. without alloying process; mechanical auxiliary parts therefor (adaptations of leads inserted in holes for press-fit connections H05K 3/308)]
3/326 . . . . [the printed circuit having integral resilient or deformable parts, e.g. tabs or parts of flexible circuits (H05K 3/365 takes precedence)]
3/328 . . . . [by welding]
3/34 . . . by soldering
3/3405 . . . . [Edge mounted components, e.g. terminals]
3/341 . . . . . [Surface mounted components]
3/3415 . . . . . . [on both sides of the substrate or combined with lead-in-hole components]
3/3421 . . . . . . [Leaded components]
3/3426 . . . . . . . [characterised by the leads]
3/3431 . . . . . . . [Leadless components]
3/3436 . . . . . . . . [having an array of bottom contacts, e.g. pad grid array or ball grid array components]
3/3442 . . . . . . . . . [having edge contacts, e.g. leadless chip capacitors, chip carriers]
3/3447 . . . . . . . . . . [Lead-in-hole components (H05K 3/3415 takes precedence)]
3/3452 . . . . . . . . . . [Solder masks]
3/3457 . . . . . . . . . . [Solder materials or compositions; Methods of application thereof]
3/3463 . . . . . . . . . . . [Solder compositions in relation to features of the printed circuit board or the mounting process]
3/3468 . . . . . . . . . . . . [Applying molten solder]
3/3473 . . . . . . . . . . . . . [Plating of solder]
3/421... Plated through-holes (or plated via connections)
3/421... [Blind plated via connections (H05K 3/422,
H05K 3/423 and H05K 3/425 take precedence)]
3/422... [characterised by electroplating method;
pretreatment therefor]
3/423... [characterised by electroless plating method]
3/424... [by direct electroplating]
3/425... [characterised by the sequence of steps for
plating the through-holes or via connections in
relation to the conductive pattern]
3/426... [initial plating of through-holes in substrates
without metal]
3/427... [initial plating of through-holes in metal-clad
substrates]
3/428... [initial plating of through-holes in substrates
having a metal pattern]
3/429... [Plated through-holes specially for multilayer
circuits, e.g. having connections to inner circuit
layers]
3/44... Manufacture insulated metal core circuits [or
other insulated electrically conductive core circuits
(H05K 3/0085, H05K 3/4641, H05K 3/4608 take precedence)]
3/445... [having insulated holes or insulated via
connections through the metal core]
3/46... Manufacturing multilayer circuits
3/4602... [characterized by a special circuit board as
a base or central core whereon additional circuit
layers are built or additional circuit boards are
manufactured; Other methods of forming or developing
circuit preforms; Transferring prefabricated
solder patterns]
3/463... [Applying solder paste, particles or
powder; Transferring prefabricated
solder patterns]
3/4641... [having integral lamination metal sheets or
special power cores]
H05K

3/4644 . . . [by building the multilayer by layer, i.e. build-up multilayer circuits (making via holes in the insulating layers H05K 3/0011; special circuit boards as base or core whereon the multilayer is built H05K 3/4602)]

3/4647 . . . . [by applying an insulating layer around previously made via studs]

3/465 . . . . [by applying an insulating layer having channels for the next circuit layer]

3/4652 . . . . [Adding a circuit layer by laminating a metal foil or a preformed metal foil pattern (H05K 3/4647 takes precedence)]

3/4655 . . . . [by using a laminate characterized by the insulating layer (general-purpose insulating materials H05K 1/02, H05K 3/4673)]

3/4658 . . . . [characterized by laminating a prefabricated metal foil pattern, e.g. by transfer]

3/4661 . . . . [Adding a circuit layer by direct wet plating, e.g. electroless plating; insulating materials adapted therefor (other insulating materials H05K 3/387)]

3/4664 . . . . [Adding a circuit layer by thick film methods, e.g. printing techniques or by other techniques for making conductive patterns by using pastes, inks or powders (H05K 3/4647 takes precedence)]

3/4667 . . . . [characterized by using an inorganic intermediate insulating layer]

3/467 . . . . [Adding a circuit layer by thin film methods (H05K 3/4647 takes precedence)]

3/4673 . . . . [Application methods or materials of intermediate insulating layers not specially adapted to any one of the previous methods of adding a circuit layer (similar methods for protective coatings H05K 3/28)]

3/4676 . . . . [Single layer compositions]

3/4679 . . . . [Aligning added circuit layers or via connections relative to previous circuit layers]

3/4682 . . . . [Manufacture of core-less build-up multilayer circuits on a temporary carrier or on a metal foil]

3/4685 . . . . [Manufacturing of cross-over conductors]

3/4688 . . . . [Composite multilayer circuits, i.e. comprising insulating layers having different properties (having a special base or central core H05K 3/4602)]

3/4691 . . . . [Rigid-flexible multilayer circuits comprising rigid and flexible layers, e.g. having in the bending regions only flexible layers]

3/4694 . . . . [Partitioned multilayer circuits having adjacent regions with different properties, e.g. by adding or inserting locally circuit layers having a higher circuit density (H05K 3/4691 takes precedence)]

3/4697 . . . . [having cavities, e.g. for mounting components (H05K 3/4691 takes precedence)]

5/00 . . . . . . . Casing, cabinets or drawers for electric apparatus

5/0004 . . . . [comprising several parts forming a closed casing]

5/0008 . . . . [assembled by screws]

5/0013 . . . . [assembled by resilient members]

5/0017 . . . . [with display or control units]

5/0021 . . . . [Side-by-side or stacked arrangements]
H05K

7/00 Constructional details common to different types of electric apparatus (casings, cabinets, drawers H05K 5/00)

7/005 . . . . . . . [arrangements of circuit components without supporting structure]
7/02 . . . . . . . Arrangements of circuit components or wiring on supporting structure
7/023 . . . . . . . [Stackable modules]
7/026 . . . . . . . [Multiple connections subassemblies]
7/04 . . . . . . . on conductive chassis
7/06 . . . . . . . on insulating boards (e.g. wiring harnesses (for printed circuits H05K 1/18, H05K 3/30))
7/08 . . . . . . . . . . . on perforated boards
7/10 . . . . . . . Plug-in assemblages of components (e.g. IC sockets)
7/1007 . . . . . . . with means for increasing contact pressure at the end of engagement of coupling parts
7/1015 . . . . . . . [having exterior leads]
7/1023 . . . . . . . [co-operating by abutting, e.g. flat pack]
7/103 . . . . . . . [co-operating by sliding, e.g. DIP carriers]
7/1038 . . . . . . . [with spring contact pieces (H05K 7/1046 takes precedence)]
7/1046 . . . . . . . [J-shaped leads]
7/1053 . . . . . . . [having interior leads]
7/1061 . . . . . . . [co-operating by abutting]
7/1069 . . . . . . . [with spring contact pieces]
7/1076 . . . . . . . [co-operating by sliding]
7/1084 . . . . . . . [pin grid array package carriers]
7/1092 . . . . . . . [with built-in components, e.g. intelligent sockets]
7/12 . . . . . . . . . . . Resilient or clamping means for holding component to structure
7/14 . . . . . . . . . . . Mounting supporting structure in casing or on frame or rack (H05K 7/18 takes precedence)
7/1401 . . . . . . . [comprising clamping or extracting means (H05K 7/10 takes precedence)]
7/1402 . . . . . . . [for securing or extracting printed circuit boards]
7/1404 . . . . . . . [by edge clamping, e.g. wedges]
7/1405 . . . . . . . [by clips or resilient members, e.g. hooks]
7/1407 . . . . . . . [by turn-bolt or screw member]
7/1408 . . . . . . . [by a unique member which latches several boards, e.g. locking bars]
7/1409 . . . . . . . [by lever-type mechanisms]
7/1411 . . . . . . . [for securing or extracting box-type drawers]
7/1412 . . . . . . . [hold down mechanisms, e.g. avionic racks]
7/1414 . . . . . . . [with power interlock]
7/1415 . . . . . . . [manual gripping tools]
7/1417 . . . . . . . [having securing means for mounting boards, plates or wiring boards (H05K 7/1461 takes precedence)]
7/1418 . . . . . . . [Card guides, e.g. grooves (H05K 7/1425 takes precedence)]
7/142 . . . . . . . [Spacers not being card guides]
7/1421 . . . . . . . [Drawers for printed circuit boards]
7/1422 . . . . . . . [Printed circuit boards receptacles, e.g. stacked structures, electronic circuit modules or box like frames]
7/1424 . . . . . . . [Card cages]
7/1425 . . . . . . . [of standardised dimensions, e.g. 19"-subrack]
7/1427 . . . . . . . [Housings]
7/1428 . . . . . . . [for small modular apparatus with terminal block]
7/1429 . . . . . . . [for circuits carrying a CPU and adapted to receive expansion cards]
7/1431 . . . . . . . [Retention mechanisms for CPU modules]
7/1432 . . . . . . . [for power drive units]
7/1434 . . . . . . . [for electronics exposed to high gravitational force; Cylindrical housings]
7/1435 . . . . . . . [Expandable constructions]
7/1438 . . . . . . . [Back panels or connecting means therefor; Terminals; Coding means to avoid wrong insertion]
7/1439 . . . . . . . [Back panel mother boards]
7/1441 . . . . . . . [with a segmented structure]
7/1442 . . . . . . . [with a radial structure]
7/1444 . . . . . . . [Complex or three-dimensional-arrangements: Stepped or dual mother boards]
7/1445 . . . . . . . [with double-sided connections]
7/1447 . . . . . . . [External wirings; Wiring ducts; Laying cables]
7/1448 . . . . . . . [with connections to the front board]
7/1449 . . . . . . . [with connections to the back board]
7/1451 . . . . . . . [with connections between circuit boards or units]
7/1452 . . . . . . . [Mounting of connectors; Switching; Reinforcing of back panels]
7/1454 . . . [Alignment mechanisms; Drawout cases]
7/1455 . . . [Coding for prevention of wrong insertion]
7/1457 . . . [Power distribution arrangements]
7/1458 . . . [Active back panels; Back panels with filtering means]
7/1459 . . . [Circuit configuration, e.g. routing signals]
7/1461 . . . [Slidable card holders; Card stiffeners; Control or display means therefor]
7/1462 . . . [for programmable logic controllers [PLC] for automation or industrial process control]
7/1464 . . . [Functional units accommodated in the same PLC module housing]
7/1465 . . . [Modular PLC assemblies with separable functional units]
7/1467 . . . [PLC mounted in a cabinet or chassis]
7/1468 . . . [Mechanical features of input/output (I/O) modules]
7/1469 . . . [Terminal blocks for connecting sensors]
7/1471 . . . [Modules for controlling actuators]
7/1472 . . . [Bus coupling modules, e.g. bus distribution modules]
7/1474 . . . [Mounting of modules, e.g. on a base or rail or wall]
7/1475 . . . [Bus assemblies for establishing communication between PLC modules]
7/1477 . . . [including backplanes]
7/1478 . . . [including a segmented bus]
7/1479 . . . [including decentralized modules, e.g. connected to other modules using fieldbus]
7/1481 . . . [User interface, e.g. status displays; Programming interface, e.g. connector for computer programming; Monitoring]
7/1482 . . . [PLC power supply; PLC accessories, e.g. for safety]
7/1484 . . . [Electrical diagrams relating to constructional features, e.g. signal routing within PLC; Provisions for disaster recovery, e.g. redundant systems]
7/1485 . . . [Servers; Data center rooms, e.g. 19-inch computer racks]
7/1487 . . . [Blade assembly, e.g. cases and inner arrangements]
7/1488 . . . [Cabinets therefore, e.g. chassis, racks]
7/1489 . . . [characterized by the mounting of blades therein, e.g. brackets, rails, trays (H05K 7/1491 takes precedence)]
7/1491 . . . [having cable management arrangements (management of optical cables G02B 6/444; in telecommunication cabinets H04Q 1/06)]
7/1492 . . . [having electrical distribution arrangements, e.g. power supply or data communications]
7/1494 . . . [having hardware for monitoring blades, e.g. keyboards, displays (methods or software therefore H05K 7/1498)]
7/1495 . . . [providing data protection in case of earthquakes, floods, storms, nuclear explosions, intrusions, fire]
7/1497 . . . [Rooms for data centers; Shipping containers therefor]
7/1498 . . . [Resource management, Optimisation arrangements, e.g. configuration, identification, tracking, physical location (thermal management H05K 7/20836)]
7/16 . . . [on hinges or pivots]
7/18 . . . [Construction of rack or frame]
7/183 . . . [support rails therefor]
7/186 . . . [for supporting telecommunication equipment (selecting apparatus H04Q 1/02)]
7/20 . . . [Modifications to facilitate cooling, ventilating, or heating]
7/20009 . . . [using a gaseous coolant in electronic enclosures (in cabinets of standardized dimensions H05K 7/20536; in server cabinets H05K 7/20709; in vehicle electronic casings H05K 7/20845; in power control electronics H05K 7/2089; in displays H05K 7/20954)]
7/20127 . . . [Natural convection]
7/20136 . . . [Forced ventilation, e.g. by fans (H05K 7/202 takes precedence)]
7/20145 . . . [Means for directing air flow, e.g. ducts, deflectors, plenum or guides]
7/20154 . . . [Heat dissipaters coupled to components]
7/20163 . . . [the components being isolated from air flow, e.g. hollow heat sinks, wind tunnels or funnels]
7/20172 . . . [Fan mounting or fan specifications]
7/20181 . . . [Filters; Louvers]
7/2019 . . . [Fan safe systems, e.g. mechanical devices for non stop cooling]
7/202 . . . [Air circulating in closed loop within enclosure wherein heat is removed through heat-exchangers]
7/20209 . . . [Thermal management, e.g. fan control]
7/20218 . . . [using a liquid coolant without phase change in electronic enclosures (in cabinets of standardized dimensions H05K 7/20536; in server cabinets H05K 7/20709; in vehicle electronic casings H05K 7/20845; in power control electronics H05K 7/2089; in displays H05K 7/20954)]
7/20236 . . . [by immersion]
7/20245 . . . [by natural convection; Thermosiphons]
7/20254 . . . [Cold plates transferring heat from heat source to coolant]
7/20263 . . . [Heat dissipaters releasing heat from coolant]
7/20272 . . . [Accessories for moving fluid, for expanding fluid, for connecting fluid conduits, for distributing fluid, for removing gas or for preventing leakage, e.g. pumps, tanks or manifolds]
7/20281 . . . [Thermal management, e.g. liquid flow control]
7/2029 . . . [using a liquid coolant with phase change in electronic enclosures (in cabinets of standardized dimensions H05K 7/20536; in server cabinets H05K 7/20709; in vehicle electronic casings H05K 7/20845; in power control electronics H05K 7/2089; in displays H05K 7/20954)]
7/203 . . . [by immersion]
7/20309 . . . [Evaporators]
7/20318 . . . [Condensers]
7/20327 . . . [Accessories for moving fluid, for connecting fluid conduits, for distributing fluid or for preventing leakage, e.g. pumps, tanks or manifolds]
7/20336 . . . [Heat pipes, e.g. wicks or capillary pumps]
7/20345 . . . [Sprayers; Atomizers]
7/20354 . . . [Refrigerating circuit comprising a compressor]
H05K

7/20363 . . . . {Refrigerating circuit comprising a sorber}
7/20372 . . . . {Cryogenic cooling; Nitrogen liquid cooling}
7/20381 . . . . {Thermal management, e.g. evaporation control}
7/2039 . . . . [characterised by the heat transfer by conduction from the heat generating element to a dissipating body (arrangements for increasing/decreasing heat-transfer, e.g. fins details, F28F 13/00)]
7/20409 . . . . [Outer radiating structures on heat dissipating housings, e.g. fins integrated with the housing]
7/20418 . . . . [the radiating structures being additional and fastened onto the housing]
7/20427 . . . . [having radiation enhancing surface treatment, e.g. black coating]
7/20436 . . . . [Inner thermal coupling elements in heat dissipating housings, e.g. protrusions or depressions integrally formed in the housing]
7/20445 . . . . [the coupling element being an additional piece, e.g. thermal standoff]
7/20454 . . . . [with a conformable or flexible structure compensating for irregularities, e.g. cushion bags, thermal paste]
7/20463 . . . . [Filling compound, e.g. potted resin]
7/20472 . . . . [Sheet interfaces]
7/20481 . . . . [characterised by the material composition exhibiting specific thermal properties]
7/2049 . . . . [Pressing means used to urge contact, e.g. springs]
7/205 . . . . [Thermal paths through the printed circuit board [PCB] (details of PCBs related to heat transfer H05K 1/0201)]
7/20509 . . . . [Cold plates, e.g. multi-component heat spreader, support plates, non closed structures]
7/20518 . . . . [Unevenly distributed heat load, e.g. different sectors at different temperatures, localised cooling, hot spots]
7/20536 . . . . [for racks or cabinets of standardized dimensions, e.g. 19-inch electronic racks]
7/20545 . . . . [Natural convection of gaseous coolant; Heat transfer by conduction from electronic boards]
7/20554 . . . . [Forced ventilation of a gaseous coolant (in closed loop H05K 7/206 or H05K 7/20609 or H05K 7/20618)]
7/20563 . . . . [within sub-racks for removing heat from electronic boards]
7/20572 . . . . [within cabinets for removing heat from sub-racks, e.g. plenum]
7/20581 . . . . [Cabinets including a drawer for fans]
7/2059 . . . . [within rooms for removing heat from cabinets, e.g. by air conditioning device]
7/206 . . . . [Air circulating in closed loop within cabinets wherein heat is removed through air-to-air heat-exchanger]
7/20609 . . . . [Air circulating in closed loop within cabinets wherein heat is removed through air-to-liquid heat-exchanger]
7/20618 . . . . [Air circulating in different modes under control of air guidance flaps]
7/20627 . . . . [Liquid coolant without phase change]
7/20636 . . . . [within sub-racks for removing heat from electronic boards]
7/20645 . . . . [within cabinets for removing heat from sub-racks]
7/20654 . . . . [within rooms for removing heat from cabinets]
7/20663 . . . . [Liquid coolant with phase change, e.g. heat pipes]
7/20672 . . . . [within sub-racks for removing heat from electronic boards]
7/20681 . . . . [within cabinets for removing heat from sub-racks]
7/2069 . . . . [within rooms for removing heat from cabinets]
7/207 . . . . [Thermal management, e.g. cabinet temperature control]
7/20709 . . . . [for server racks or cabinets; for data centers, e.g. 19-inch computer racks]
7/20718 . . . . [Forced ventilation of a gaseous coolant (in closed loop H05K 7/20754)]
7/20727 . . . . [within server blades for removing heat from heat source]
7/20736 . . . . [within cabinets for removing heat from server blades]
7/20745 . . . . [within rooms for removing heat from cabinets, e.g. by air conditioning device]
7/20754 . . . . [Air circulating in closed loop within cabinets]
7/20763 . . . . [Liquid cooling without phase change]
7/20772 . . . . [within server blades for removing heat from heat source]
7/20781 . . . . [within cabinets for removing heat from server blades]
7/2079 . . . . [within rooms for removing heat from cabinets]
7/208 . . . . [Liquid cooling with phase change]
7/20809 . . . . [within server blades for removing heat from heat source]
7/20818 . . . . [within cabinets for removing heat from server blades]
7/20827 . . . . [within rooms for removing heat from cabinets, e.g. air conditioning devices]
7/20836 . . . . [Thermal management, e.g. server temperature control]
7/20845 . . . . [for vehicle electronic casings]
7/20854 . . . . [Heat transfer by conduction from internal heat source to heat radiating structure (H05K 7/20863 takes precedence)]
7/20863 . . . . [Forced ventilation, e.g. on heat dissipaters coupled to components]
7/20872 . . . . [Liquid coolant without phase change]
7/20881 . . . . [Liquid coolant with phase change]
7/2089 . . . . [for power electronics, e.g. for inverters for controlling motor]
7/209 . . . . [Heat transfer by conduction from internal heat source to heat radiating structure (H05K 7/20909 takes precedence)]
7/20909 . . . . [Forced ventilation, e.g. on heat dissipaters coupled to components]
7/20918 . . . . [the components being isolated from air flow, e.g. hollow heat sinks, wind tunnels or funnels]
7/20927 . . . . [Liquid coolant without phase change]
7/20936 . . . . [Liquid coolant with phase change]
7/20945 . . . . [Thermal management, e.g. inverter temperature control]
7/20954 . . . . [for display panels]
9/00 Screwing of apparatus or components against electric or magnetic fields (devices for absorbing radiation from an antenna H01Q 17/00)

9/0001 . . . (Rooms or chambers (anechoic chambers G01R 29/0821))

9/0003 . . . (Shielded walls, floors, ceilings, e.g. wallpaper, wall panel, electro-conductive plaster, concrete, cement, mortar)

9/0005 . . . (Shielded windows)

9/0007 . . . (Casing (standardised racks H05K 9/0062))

9/0009 . . . (with provisions to reduce EMI leakage through the joining parts)

9/0015 . . . (Gaskets or seals)

9/0016 . . . (having a spring contact)

9/0018 . . . (with provisions to reduce aperture leakages in walls, e.g. terminals, connectors, cables)

9/002 . . . (with localised screening)

9/0022 . . . (of components mounted on printed circuit boards [PCB] (shields integrated within component packages H01L 23/552; shields integrated within PCB H05K 1/0218))

9/0024 . . . (Shield cases mounted on a PCB, e.g. cans, caps, conformal shields)

9/0026 . . . (integrimly formed from metal sheet)

9/0028 . . . (with retainers or specific soldering features)

9/003 . . . (made from electro-conductive plastic material or combining different shielding materials)

9/0032 . . . (having multiple parts, e.g. frames mating with lids)

9/0033 . . . (disposed on both PCB faces)

9/0035 . . . (with retainers mounted beforehand on the PCB, e.g. clips)

9/0037 . . . (Housings with compartments containing a PCB, e.g. partitioning walls)

9/0039 . . . (Ground layout on printed circuit board)

9/0041 . . . (Ventilation panels having provisions for screening)

9/0043 . . . (being flexible containers, e.g. pouch, pocket, bag)

9/0045 . . . (being rigid plastic containers having a coating of shielding material)

9/0047 . . . (being rigid plastic containers having conductive particles, fibres or mesh embedded therein)

9/0049 . . . (being metallic containers)

9/005 . . . (being nesting containers)

9/0052 . . . (Shielding other than Faraday cages)

9/0054 . . . (specially adapted for display applications)

9/0056 . . . (specially adapted for microwave applications)

9/0058 . . . (specially adapted for optoelectronic applications)

9/006 . . . (specially adapted for signal processing applications, e.g. CATV, tuner, antennas amplifier)

10/00 Arrangements for improving the operating reliability of electronic equipment, e.g. by providing a similar standby unit

11/00 Combinations of a radio or television receiver with apparatus having a different main function (combined with clocks G04B 47/00; controlled by a clock G04C 21/28)

11/02 . . . (with vehicles)

13/00 Apparatus or processes specially adapted for manufacturing or adjusting assemblages of electric components

13/0007 . . . (using handtools (for mounting on a circuit board H05K 13/03447))

13/0015 . . . (Orientation; Alignment; Positioning)

13/003 . . . (Placing of components on belts holding the terminals)

13/0038 . . . (placing the components in a predetermined order)
Arrangements for assisting the manual mounting of components, e.g. special tables or light spots indicating the place for mounting.

Tools for holding the circuit boards during processing; handling transport of printed circuit boards.

[Warning]

Groups H05K 13/0056, H05K 13/0061, H05K 13/0069, H05K 13/0076 should be considered in order to perform a complete search.

Containers and magazines for components, e.g. tube-like magazines.

Treatment of the terminal leads as a separate operation (during transport H05K 13/0076; during mounting H05K 13/04).

Feeding of components

[Warning]

Group H05K 13/021 is impacted by reclassification into group H05K 13/0215. Groups H05K 13/021 and H05K 13/0215 should be considered in order to perform a complete search.

Interconnecting of containers, e.g. splicing of tapes.

[Warning]

Group H05K 13/0215 is impacted by reclassification into group H05K 13/0215. Groups H05K 13/021 and H05K 13/0215 should be considered in order to perform a complete search.

[Warning]

Group H05K 13/041 is incomplete pending reclassification of documents from groups H05K 13/0404, H05K 13/0413 and H05K 13/0452. All groups listed in this Warning should be considered in order to perform a complete search.

Sucking devices.

[Warning]

Group H05K 13/0409 is incomplete pending reclassification of documents from group H05K 13/0408. Group H05K 13/0408 is also impacted by reclassification into group H05K 13/0409. Groups H05K 13/0404, H05K 13/0408 and H05K 13/0409 should be considered in order to perform a complete search.

Having multiple pick-up tools.

[Warning]

Group H05K 13/041 is incomplete pending reclassification of documents from groups H05K 13/0404, H05K 13/0413 and H05K 13/0452. All groups listed in this Warning should be considered in order to perform a complete search.
WARNING

Group H05K 13/0411 is incomplete pending reclassification of documents from groups H05K 13/0404 and H05K 13/0452.
Groups H05K 13/0404, H05K 13/0452 and H05K 13/0411 should be considered in order to perform a complete search.

Group H05K 13/0413 is incomplete pending reclassification of documents from groups H05K 13/0404 and H05K 13/0452.
Group H05K 13/0413 is also impacted by reclassification into groups H05K 13/0406 and H05K 13/041.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/0417 is impacted by reclassification into group H05K 13/0419.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0419 is incomplete pending reclassification of documents from group H05K 13/0417.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0421 is incomplete pending reclassification of documents from group H05K 13/0417.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0426 is impacted by reclassification into group H05K 13/0419.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0421 is impacted by reclassification into group H05K 13/0417.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0447 is incomplete pending reclassification of documents from group H05K 13/0417.
Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

Group H05K 13/0452 is impacted by reclassification into groups H05K 13/0406, H05K 13/0411, H05K 13/0413 and H05K 13/0414.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/0456 is impacted by reclassification into group H05K 13/046.
Group H05K 13/0465 is impacted by reclassification into group H05K 13/0469.
Group H05K 13/0469 is impacted by reclassification into group H05K 13/0465.
Groups H05K 13/0473 and H05K 13/0478 are impacted by reclassification into groups H05K 13/046 and H05K 13/041.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/0482 is impacted by reclassification into group H05K 13/0486.
Groups H05K 13/0491 and H05K 13/0495 are impacted by reclassification into group H05K 13/0482.
Group H05K 13/0495 is impacted by reclassification into group H05K 13/0491.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/0498 is impacted by reclassification into group H05K 13/050.
Group H05K 13/050 is impacted by reclassification into group H05K 13/0498.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/081 is impacted by reclassification into groups H05K 13/08, H05K 13/081, H05K 13/0812, H05K 13/0813, H05K 13/0815, H05K 13/0817, H05K 13/0818, H05K 13/082, H05K 13/083, H05K 13/084, H05K 13/085, H05K 13/0853, H05K 13/0857, H05K 13/086, H05K 13/087, H05K 13/0882, H05K 13/0885, H05K 13/0888, H05K 13/089 and H05K 13/0895.
All groups listed in this Warning should be considered in order to perform a complete search.

Group H05K 13/081 is impacted by reclassification into group H05K 13/08.
Groups H05K 13/08 and H05K 13/081 should be considered in order to perform a complete search.
13/0812 . . . [the monitoring devices being integrated in the mounting machine, e.g. for monitoring components, leads, component placement]

**WARNING**

Group H05K 13/0812 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0812 should be considered in order to perform a complete search.

13/0813 . . . [Controlling of single components prior to mounting, e.g. orientation, component geometry (H05K 13/0812 takes precedence)]

**WARNING**

Group H05K 13/0813 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0813 should be considered in order to perform a complete search.

13/0815 . . . [Controlling of component placement on the substrate during or after manufacturing]

**WARNING**

Group H05K 13/0815 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0815 should be considered in order to perform a complete search.

13/0817 . . . [Monitoring of soldering processes (inspection of solder joints or of printed solder paste G01N 21/95684)]

**WARNING**

Group H05K 13/0817 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0817 should be considered in order to perform a complete search.

13/0818 . . . [Setup of monitoring devices prior to starting mounting operations; Teaching of monitoring devices for specific products; Compensation of drifts during operation, e.g. due to temperature shifts]

**WARNING**

Group H05K 13/0818 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0818 should be considered in order to perform a complete search.

13/082 . . . [Integration of non-optical monitoring devices, i.e. using non-optical inspection means, e.g. electrical means, mechanical means or X-rays]

**WARNING**

Group H05K 13/082 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/082 should be considered in order to perform a complete search.

13/083 . . . [Quality monitoring using results from monitoring devices, e.g. feedback loops (H05K 13/084 takes precedence)]

**WARNING**

Group H05K 13/083 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/083 should be considered in order to perform a complete search.

13/084 . . . [Product tracking, e.g. of substrates during the manufacturing process; Component traceability]

**WARNING**

Group H05K 13/084 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/084 should be considered in order to perform a complete search.

13/085 . . . [Production planning, e.g. of allocation of products to machines, of mounting sequences at machine or facility level]

**WARNING**

Group H05K 13/085 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/085 should be considered in order to perform a complete search.

13/0853 . . . [Determination of transport trajectories inside mounting machines]

**WARNING**

Group H05K 13/0853 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0853 should be considered in order to perform a complete search.
13/0857 . . . {Product-specific machine setup; Changeover of machines or assembly lines to new product type}

**WARNING**

Group H05K 13/0857 is incomplete pending reclassification of documents from group H05K 13/08.
Groups H05K 13/08 and H05K 13/0857 should be considered in order to perform a complete search.

13/086 . . . {Supply management, e.g. supply of components or of substrates}

**WARNING**

Group H05K 13/086 is incomplete pending reclassification of documents from group H05K 13/08.
Groups H05K 13/08 and H05K 13/086 should be considered in order to perform a complete search.

13/087 . . . {Equipment tracking or labelling, e.g. tracking of nozzles, feeders or mounting heads}

**WARNING**

Group H05K 13/087 is incomplete pending reclassification of documents from group H05K 13/08.
Groups H05K 13/08 and H05K 13/087 should be considered in order to perform a complete search.

13/0882 . . . {Control systems for mounting machines or assembly lines, e.g. centralized control, remote links, programming of apparatus and processes as such (H05K 13/083 takes precedence)}

**WARNING**

Group H05K 13/0882 is incomplete pending reclassification of documents from group H05K 13/08.
Groups H05K 13/08 and H05K 13/0882 should be considered in order to perform a complete search.

13/0885 . . . {Power supply}

**WARNING**

Group H05K 13/0885 is incomplete pending reclassification of documents from group H05K 13/08.
Groups H05K 13/08 and H05K 13/0885 should be considered in order to perform a complete search.

2201/00 Indexing scheme relating to printed circuits covered by H05K 1/00

2201/01 . . . Dielectrics
2201/0104 . . . Properties and characteristics in general
2201/0108 . . . Transparent
2201/0112 . . . Absorbing light, e.g. dielectric layer with carbon filler for laser processing
2201/0116 . . . Porous, e.g. foam
2201/012 . . . Flame-retardant; Preventing of inflammation
2201/0125 . . . Shrinkable, e.g. heat-shrinkable polymer
2201/0129 . . . Thermoplastic polymer, e.g. auto-adhesive layer; Shaping of thermoplastic polymer
2201/0133 . . . Elastomeric or compliant polymer (elastomeric conductor H05K 2201/0314)
2201/0137 . . . Materials
2201/0141 . . . Liquid crystal polymer [LCP]
2201/0145 . . . Polyester, e.g. polyethylene terephthalate [PET], polyethylene naphthalate [PEN]
2201/015 . . . Fluoropolymer, e.g. polytetrafluoroethylene [PTFE]
2201/0154 . . . Polymide
2201/0158 . . . Polyalkene or polyolefin, e.g. polyethylene [PE], polypropylene [PP]
2201/0162 . . . Silicon containing polymer, e.g. silicone
2201/0166 . . . Polymeric layer used for special processing, e.g. resist for etching insulating material or photoresist used as a mask during plasma etching
2201/017 . . . Glass ceramic coating, e.g. formed on inorganic substrate (inorganic, non-metallic substrates H05K 1/0306)
2201/0382 . . . Continuously deformed conductors
2201/0385 . . . Displaced conductors
2201/0388 . . . Other aspects of conductors
2201/0391 . . . Using different types of conductors
2201/0394 . . . Conductor crossing over a hole in the substrate
2201/0397 . . . Tab (forming integral conductive tabs H05K 3/4092)

2201/04 . . . Assemblies of printed circuits
2201/041 . . . Stacked PCBs, i.e. having neither an empty space nor mounted components in between
2201/042 . . . Stacked spaced PCBs; Planar parts of folded flexible circuits having mounted components in between or spaced from each other
2201/043 . . . Stacked PCBs with their backs attached to each other without electrical connection
2201/044 . . . Details of backplane or midplane for mounting orthogonal PCBs
2201/045 . . . Hierarchy auxiliary PCB, i.e. more than two levels of hierarchy for daughter PCBs are important
2201/046 . . . Planar parts of folded PCBs making an angle relative to each other (assembling printed circuits perpendicularly to each other H05K 3/366)
2201/047 . . . Box-like arrangements of PCBs
2201/048 . . . Second PCB mounted on first PCB by inserting in window or holes of the first PCB
2201/049 . . . PCB for one component, e.g. for mounting onto mother PCB

2201/05 . . . Flexible printed circuits [FPCs]
2201/051 . . . Rolled
2201/052 . . . Branched
2201/053 . . . Tails
2201/055 . . . Folded back on itself
2201/056 . . . Folded around rigid support or component
2201/057 . . . Shape retainable
2201/058 . . . Direct connection between two or more FPCs or between flexible parts of rigid PCBs

2201/06 . . . Thermal details
2201/062 . . . Means for thermal insulation, e.g. for protection of parts
2201/064 . . . Fluid cooling, e.g. by integral pipes
2201/066 . . . Heatsink mounted on the surface of the PCB (heatsink inserted in the PCB H05K 2201/10416)
2201/068 . . . wherein the coefficient of thermal expansion is important

2201/07 . . . Electric details
2201/070 . . . Shielding
2201/0715 . . . provided by an outer layer of PCB
2201/0723 . . . provided by an inner layer of PCB
2201/073 . . . High voltage adaptations (overvoltage protection H05K 1/0257)
2201/0738 . . . Use of voltage responsive materials, e.g. voltage switchable dielectric or varistor materials
2201/0746 . . . Protection against transients, e.g. layout adapted for plugging of connector
2201/0753 . . . Insulation
2201/0761 . . . Insulation resistance, e.g. of the surface of the PCB between the conductors
2201/0769 . . . Anti metal-migration, e.g. avoiding tin whisker growth
2201/0776 . . . Resistance and impedance

2201/0784 . . . Uniform resistance, i.e. equalizing the resistance of a number of conductors
2201/0792 . . . Means against parasitic impedance; Means against eddy currents

2201/08 . . . Magnetic details
2201/083 . . . Magnetic materials
2201/086 . . . for inductive purposes, e.g. printed inductor with ferrite core

2201/09 . . . Shape and layout
2201/09009 . . . Substrate related
2201/09018 . . . Rigid curved substrate
2201/09027 . . . Non-rectangular flat PCB, e.g. circular
2201/09036 . . . Recesses or grooves in insulating substrate (recess in metallic substrate H05K 2201/09745)
2201/09045 . . . Locally raised area or protrusion of insulating substrate (rigid curved substrate H05K 2201/09918)
2201/09054 . . . Raised area or protrusion of metal substrate
2201/09063 . . . Holes or slots in insulating substrate not used for electrical connections
2201/09072 . . . Hole or recess under component or special relationship between hole and component
2201/09081 . . . Tongue or tail integrated in planar structure, e.g. obtained by cutting from the planar structure
2201/0909 . . . Preformed cutting or breaking line
2201/091 . . . Locally and permanently deformed areas
2201/09109 . . . Locally detached layers, e.g. in multilayer
2201/09118 . . . Moulded substrate
2201/09127 . . . PCB or component having an integral separable or breakable part
2201/09136 . . . Means for correcting warpage
2201/09145 . . . Edge details
2201/09154 . . . Bevelled, chamfered or tapered edge
2201/09163 . . . Slotted edge
2201/09172 . . . Notches between edge pads
2201/09181 . . . Notches in edge pads
2201/0919 . . . Exposing inner circuit layers or metal planes at the side edge of the PCB or at the walls of large holes (shielding provided by an inner layer of PCB H05K 2201/0723)
2201/092 . . . Exposing inner circuit layers or metal planes at the walls of high aspect ratio holes (forming plated-through holes H05K 3/42; cutting around hole H05K 2203/0242)
2201/09209 . . . Shape and layout details of conductors
2201/09218 . . . Conductive traces
2201/09227 . . . Layout details of a plurality of traces, e.g. escape layout for Ball Grid Array [BGA] mounting
2201/09236 . . . Parallel layout (layout of balanced signal pairs H05K 1/0245; superposed layout H05K 2201/09672)
2201/09245 . . . Crossing layout (alternating conductors H05K 2201/097)
2201/09254 . . . Branched layout
2201/09263 . . . Meander
2201/09272 . . . Layout details of angles or corners
2201/09281 . . . Layout details of a single conductor (meander H05K 2201/09263; layout details of angles or corners H05K 2201/09272)
2201/0929 . . . Conductive planes
Conductive through-holes or vias

Pads and lands

Shape of non-curved single flat metallic pad, land or exposed part thereof; Shape of electrode of leadless component (notches in edge pads H05K 2201/09181)

Curved pads, e.g. semi-circular or elliptical pads or lands

Array of pads or lands differing from one another, e.g. in size, pitch, thickness; Using different connections on the pads (using different types of conductors H05K 2201/09391)

Multiple rows of pads, lands, terminals or dummy patterns; Multiple rows of mounted components

Special orientation of pads, lands or terminals of component, e.g. radial or polygonal orientation

Special relation between the location or dimension of a pad or land and the location or dimension of a terminal

Pads or lands on permanent coating which covers the other conductors

Pads for connections not located at the edge of the PCB, e.g. for flexible circuits

Inner lands, i.e. lands around via or plated through-hole in internal layer of multilayer PCB

Partial lands, i.e. lands or conductive rings not completely surrounding the hole (landless plated-through hole or via H05K 2201/09545)

Recessed pad for surface mounting (recess in pad H05K 2201/09745); Recessed electrode of component

Via in pad; Pad over filled via (if used for surface mounting H05K 2201/09113)

Pad close to a hole, not surrounding the hole (if used for surface mounting H05K 2201/09114)

Conductive through-holes or vias

Blind vias, i.e. vias having one side closed

Deep blind vias, i.e. blind vias connecting the surface circuit to circuit layers deeper than the first buried circuit layer

Inverse blind vias, i.e. bottoms outwards in multilayer PCB; Blind vias in centre of PCB having opposed bottoms

Buried plated through-holes, i.e. plated through-holes formed in a core before lamination

Plated through-holes or blind vias without lands

Via connected to metal substrate

Metal filled via (plated through-hole filled with insulating material H05K 2201/0959)

Soldered plated through-hole in the final product (soldering lead-in-hole components H05K 3/347)

Applying an insulating coating on the walls of holes

Plated through-holes or plated blind vias filled with insulating material

Vertically aligned vias, holes or stacked vias

Via grid, i.e. two-dimensional array of vias or holes in a single plane (interposers H05K 2201/10378)

Via fence, i.e. one-dimensional array of vias

Special connections between adjacent vias, not for grounding vias (redundant conductors or connections H05K 2201/0979)

Details of adjacent, not connected vias

Patterning on via walls; Plural lands around one hole

covering at least two types of conductors provided for in H05K 2201/09218 - H05K 2201/095

Divided layout, i.e. conductors divided in two or more parts (branched layout H05K 2201/09254)

Superposed layout, i.e. in different planes (parallel traces in one plane H05K 2201/09236)

Mesh conductors, e.g. as a ground plane

Apertured conductors

Alternating conductors, e.g. alternating different shaped pads, twisted pairs; Alternating components

Staggered pads, lands or terminals; Parallel conductors in different planes

Clearance holes

Varying width along a single conductor; Conductors or pads having different widths

Varying thickness of a single conductor; Conductors in the same plane having different thicknesses

Recess in conductor, e.g. in pad or in metallic substrate

Connector integrally incorporated in the PCB or in housing (mounted connector H05K 2201/10189)

Printed component having superposed conductors, but integrated in one circuit layer

Conditioners directly under a component but not electrically connected to the component (cooling of mounted components by printed thermal vias H05K 1/0206)
Details of components or other objects attached to Types of components groups for in H05K 2201/09009; Other shape and layout details not provided - H05K 2201/09209

- Printed or non-printed battery
- Non-printed resistor
- Non-printed capacitor as PCB; Circuit printed on or in housing, e.g. housing or differently different functions; Boundary lines therefore;
- Partitioned, e.g. portions of a PCB dedicated to e.g. small PCBs
- Programming circuit by using small elements, of PCB, or by using different sets of edge pads
- More mounting possibilities, e.g. on same place via grid, or anisotropic interposer
- Marks, inscriptions, etc. for information
- Machine readable code, e.g. bar code
- Marks, inscriptions, etc. for information
- Universal aspects, e.g. universal inner layers or via grid, or anisotropic interposer
- More mounting possibilities, e.g. on same place of PCB, or by using different sets of edge pads
- Programming circuit by using small elements, e.g. small PCBs
- Partitioned, e.g. portions of a PCB dedicated to different functions; Boundary lines therefore; Portions of a PCB being processed separately or differently
- Metallised walls
- Circuit printed on or in housing, e.g. housing as PCB; Circuit printed on the case of a component; PCB affixed to housing
- Details of components or other objects attached to or integrated in a printed circuit board

- Types of components
- Non-printed capacitor
- Non-printed resistor
- Non-printed inductor
- Printed or non-printed battery
- Mounted network component having plural terminals
- Switch
- Non-printed filter

- Non-printed resonator
- Non-printed oscillator
- Electromechanical or electro-acoustic component, e.g. microphone
- Electromotor
- Component for radio transmission, e.g. Radio Frequency Identification Tag [RFID]
- Light emitting diode [LED]
- Lamp
- Optical component, e.g. opto-electronic component
- Display
- Liquid Crystal display [LCD]
- Solar cell
- Sensor
- Memory
- Transistor
- Diode
- Fuse
- Non-printed connector
- Variable component, e.g. variable resistor
- Dummy component, dummy PCB or template, e.g. for monitoring, controlling of processes, comparing, scanning
- Programmable component
- Thermoelectric component
- Other objects, e.g. metallic pieces
- Metallic balls (solder balls H05K 2203/041)
- Metallic cylinders (small solder preforms other than balls H05K 2203/0415)
- Metallic discs (small solder preforms other than balls H05K 2203/0415)
- Hollow pieces of metal, e.g. used in connection between component and PCB
- Metalic coils or springs, e.g. as part of a connection element
- Busbars, i.e. thick metal bars mounted on the PCB as high-current conductors (metal strips H05K 2201/034)
- Thin metal strips as connectors or conductors
- Metal wires as connectors or conductors
- Metallic connector elements partly mounted in a hole of the PCB
- Pin-in-hole mounted pins
- Surface mounted metallic connector elements
- Surface mounted metallic pins
- Individual female type metallic connector elements
- Edge terminals, i.e. separate pieces of metal attached to the edge of the PCB (tab H05K 2201/0397)
- Fuzz's as connector elements, i.e. small pieces of metallic fiber to make connection
- Cables
- Jumpers, i.e. non-printed cross-over connections
- Shields or metal cases
- Interposers
- Clip leads; Terminals gripping the edge of a substrate
2201/10393 . . . Clamping a component by an element or a set of elements
2201/10401 . . . Eyelets, i.e. rings inserted into a hole through a circuit board
2201/10409 . . . Screws
2201/10416 . . . Metallic blocks or heatsinks completely inserted in a PCB (metallic supports H05K 3/3061)
2201/10424 . . . Frame holders
2201/10431 . . . Details of mounted components (printed components H05K 1/16)
2201/10439 . . . Position of a single component
2201/10446 . . . Mounted on an edge (soldering edge mounted components H05K 3/3405; edge terminals H05K 2201/1034)
2201/10454 . . . Vertically mounted
2201/10462 . . . Flat component oriented parallel to the PCB surface
2201/10469 . . . Asymmetrically mounted component
2201/10477 . . . Inverted
2201/10484 . . . Obliquely mounted
2201/10492 . . . Electrically connected to another device (mounted components directly electrically connected to each other H05K 2201/1053)
2201/105 . . . Mechanically attached to another device (attached components H05K 2201/10537)
2201/10507 . . . Involving several components
2201/10515 . . . Stacked components
2201/10522 . . . Adjacent components
2201/1053 . . . Mounted components directly electrically connected to each other, i.e. not via the PCB
2201/10537 . . . Attached components
2201/10545 . . . Related components mounted on both sides of the PCB
2201/10553 . . . Component over metal, i.e. metal plate in between bottom of component and surface of PCB
2201/1056 . . . Metal over component, i.e. metal plate over component mounted on or embedded in PCB
2201/10568 . . . Integral adaptations of a component or an auxiliary PCB for mounting, e.g. integral spacer element
2201/10575 . . . Insulating foil under component (permanent spacer or stand-off H05K 2201/2036)
2201/10583 . . . Cylindrically shaped component; Fixing means therefore
2201/1059 . . . Connections made by press-fit insertion
2201/10598 . . . Means for fastening a component, a casing or a heat sink whereby a pressure is exerted on the component towards the PCB
2201/10606 . . . Permanent holder for component or auxiliary PCB mounted on a PCB (clamping a component by an element or a set of elements H05K 2201/10393)
2201/10613 . . . Details of electrical connections of non-printed components, e.g. special leads
2201/10621 . . . Components characterised by their electrical contacts
2201/10628 . . . Leaded surface mounted device (soldering surface mounted ledged components H05K 3/3421)
2201/10636 . . . Leadless chip, e.g. chip capacitor or resistor
2201/10645 . . . Disc shaped leadless component
2201/10651 . . . Component having two leads, e.g. resistor, capacitor
2201/10659 . . . Different types of terminals for the same component, e.g. solder balls combined with leads
2201/10666 . . . Plated through-hole for surface mounting on PCB
2201/10674 . . . Flip chip
2201/10681 . . . Tape Carrier Package [TCP]; Flexible sheet connector
2201/10689 . . . Leaded Integrated Circuit [IC] package, e.g. dual-in-line [DIL]
2201/10704 . . . Pin grid array [PGA]
2201/10712 . . . Via grid array, e.g. via grid array capacitor
2201/10719 . . . Land grid array [LGA]
2201/10727 . . . Leadless chip carrier [LCC], e.g. chip-modules for cards
2201/10734 . . . Ball grid array [BGA]; Bump grid array
2201/10742 . . . Details of leads
2201/1075 . . . Shape details
2201/10757 . . . Bent leads
2201/10765 . . . Leads folded back, i.e. bent with an angle of 180 deg
2201/10772 . . . Leads of a surface mounted component bent for providing a gap between the lead and the pad during soldering
2201/1078 . . . Leads having locally deformed portion, e.g. for retention
2201/10787 . . . Leads having protrusions, e.g. for retention or insert stop
2201/10795 . . . Details of lead tips, e.g. pointed
2201/10803 . . . Tapered leads, i.e. leads having changing width or diameter
2201/1081 . . . Special cross-section of a lead; Different cross-sections of different leads; Matching cross-section, e.g. matched to a land
2201/10818 . . . Flat leads
2201/10825 . . . Distorted or twisted flat leads, i.e. deformed by torque
2201/10833 . . . having a curved or folded cross-section
2201/1084 . . . Notched leads
2201/10848 . . . Thinned leads
2201/10856 . . . Divided leads, e.g. by slot in length direction of lead, or by branching of the lead
2201/10863 . . . Adaptations of leads or holes for facilitating insertion
2201/10871 . . . Leads having an integral insert stop
2201/10878 . . . Means for retention of a lead in a hole
2201/10886 . . . Other details
2201/10893 . . . Grouped leads, i.e. element comprising multiple leads distributed around but not through a common insulator
2201/10901 . . . Lead partly inserted in hole or via
2201/10909 . . . Materials of terminal, e.g. of leads or electrodes of components
2201/10916 . . . Terminals having auxiliary metallic piece, e.g. for soldering
2201/10924 . . . Leads formed from a punched metal foil (affixing a prefabricated self-supporting metal foil pattern H05K 3/202)
Indexing scheme relating to apparatus or processes for manufacturing printed circuits covered by **H05K**

- **Tools for processing; Objects used during processing**
- **Patterning, e.g. plating or etching**
- **Dispenser, e.g. for solder paste, for supplying conductive paste for screen printing or for filling holes**
- **Inkjet printing, e.g. for printing insulating material or resist (using ink-jet printing to form a conductive pattern)**
- **Drum, e.g. rotary drum or dispenser with a plurality of openings**
- **Blade or squeegee, e.g. for screen printing or filling of holes**
- **Using a roller; Specific shape thereof; Providing locally adhesive portions thereof**
- **Temporary metallic carrier, e.g. for transferring material (affixing a prefabricated conductor pattern formed by electroplating or electroforming on a metallic carrier)**
- **Temporary polymeric carrier or foil, e.g. for processing or transferring**
- **Temporary inorganic, non-metallic carrier, e.g. for processing or transferring**
- **Holder for holding a Printed Circuit Board (PCB) during processing, e.g. during screen printing**
- **Using a temporary frame during processing**
- **Template for holding a PCB having mounted components thereon**
- **Projectile, e.g. for perforating substrate**
- **Using a temporary spacer element or stand-off during processing**
- **Mask formed or laid on PCB, the mask having recesses or openings specially designed for mounting components or body parts thereof**
- **Tool for a process not provided for in H05K 3/00; Using tape or non-metallic foil in a process, e.g. mounting components or body parts thereof**
- **Using a temporary spacer element or stand-off during processing**
- **Back-up or entry material, e.g. for mechanical drilling**
- **Perforating**
- **Cutting, sawing, milling or shearing**
- **Laminating followed by cutting or slicing perpendicular to plane of the laminate; Embedding wires in an object and cutting or slicing the object perpendicular to direction of the wires**
- **Cutting around hole, e.g. for disconnecting land or Plated Through-Hole (PTH) or for partly removing a PTH**
- **Abrading, e.g. grinding or sand blasting (deburring, rounding, bevelling or smoothing conductor edges)**
- **Brushing, e.g. cleaning the conductive pattern by brushing or wiping**
- **Peeling insulating layer, e.g. foil, or separating mask**
- **Mechanical force other than pressure, e.g. shearing or pulling**
- **Flat pressure, e.g. for connecting terminals with anisotropic conductive adhesive**
- **Using ultrasound, e.g. for cleaning, soldering or wet treatment**
- **Using vibration, e.g. during soldering or screen printing**
Soldering with different solders, e.g. two different solders on two sides of the PCB

Molten solder just before placing the component

Self-alignment during soldering; Terminals, pads or shape of solder adapted therefor

Tacky flux, e.g. for adhering components during mounting

Wire bonding

Cold welding

Patterning and lithography; Masks; Details of resist

Patterning and lithography

Double exposure of the same photosensitive layer

Flood exposure

Diffusion patterning

Photodevelopable thick film, e.g. conductive or insulating paste

Electrographic patterning

Magnetographic patterning

Using an adhesive pattern

Patterning by phototackifying or by photopatterning adhesive

Patterning during transfer, i.e. without preformed pattern, e.g. by using a die, a programmed tool or a laser

Decalcomania, i.e. transfer of a pattern detached from its carrier before affixing the pattern to the substrate

Offset printing, i.e. transfer of a pattern from a carrier onto the substrate by using an intermediate member

Transfer of pre-fabricated insulating pattern

Continuous temporary metal layer over resist, e.g. for selective electroplating

Continuous temporary metal layer over metal pattern (reinforcing the conductive pattern characterised by the electroplating method H05K 3/241)

Pattern for applying drops or paste; Applying a pattern made of drops or paste (using thick film techniques to apply conductive material by using a substrate with a shape pattern H05K 3/1258)

Exposure mask directly printed on the PCB

Metal used as mask for etching vias, e.g. by laser ablation

Non-printed masks

Using an artwork, i.e. a photomask for exposing photosensitive layers

Details of resist

Resist used only for applying catalyst, not for plating itself

Resist used for applying paste, ink or powder

Dual purpose resist, e.g. etch resist used as solder resist, solder resist used as plating resist

Stacked resist layers used for different processes

Double layer of resist having the same pattern

Additional resists used for the same purpose but in different areas, i.e. not stacked

Coating by resist, i.e. resist used as mask for application of insulating coating or of second resist
Lamination

of previously made multilayered subassemblies (laminating only or mainly similar single-sided circuit boards H05K 3/4617; laminating only or mainly similar double-sided circuit boards H05K 3/462)

of preperforated insulating layer

Binding insulating layers without adhesive, e.g. by local heating or welding, before lamination of the whole PCB

Transfer laminating of insulating material, e.g. resist as a whole layer, not as a pattern (transferring an insulating pattern H05K 2203/0537)

Features of the lamination process or of the lamination press or of the pattern (transferring an insulating pattern H05K 2203/0537)

of previously made multilayered subassemblies (laminating only or mainly similar single-sided circuit boards H05K 3/4617; laminating only or mainly similar double-sided circuit boards H05K 3/462)

Lamination

... Second resist used as mask for selective stripping of first resist

... Second resist used as pattern over first resist

... Organic non-polymeric coating, e.g. for inhibiting corrosion thereby preserving solderability

... Insulating resist or coating with special shaped edges

... Resist applied over the edges or sides of conductors, e.g. for protection during etching or plating (coating over pads H05K 2201/09818)

2203/068 . . . Features of the lamination press or of the lamination process, e.g. using special separator sheets

2203/07 . . . Treatments involving liquids, e.g. plating, rinsing

2203/0703 . . . Plating

2203/0706 . . . Inactivating or removing catalyst, e.g. on surface of resist

2203/0709 . . . Catalytic ink or adhesive for electroless plating (catalyst filler H05K 2201/0236)

2203/0713 . . . Plating poison, e.g. for selective plating or for preventing plating on resist

2203/0716 . . . Metallic plating catalysts, e.g. for direct electroplating of through holes; SENSITISING OR ACTIVATING METALLIC PLATING CATALYSTS

2203/0717 . . . Electroless plating, e.g. finish plating or initial plating

2203/0722 . . . Electroplating, e.g. finish plating

2203/0726 . . . Electroforming, i.e. electroplating on a metallic carrier thereby forming a self-supporting structure

2203/073 . . . Displacement plating, substitution plating or immersion plating, e.g. for finishing plating

2203/0733 . . . Method for plating stud vias, i.e. massive vias formed by plating the bottom of a hole without plating on the walls

2203/0736 . . . Methods for applying liquids, e.g. spraying

2203/074 . . . Features related to the fluid pressure

2203/0743 . . . Mechanical agitation of fluid, e.g. during cleaning of the conductive pattern

2203/0746 . . . Local treatment using a fluid jet, e.g. for removing or cleaning material; Providing mechanical pressure using a fluid jet

2203/075 . . . Global treatment of printed circuits by fluid spraying, e.g. cleaning a conductive pattern using nozzles

2203/0753 . . . Reversing fluid direction, e.g. in holes

2203/0756 . . . Uses of liquids, e.g. rinsing, coating, dissolving

2203/0759 . . . Forming a polymer layer by liquid coating, e.g. a non-metallic protective coating or an organic bonding layer

2203/0763 . . . Treating individual holes or single row of holes, e.g. by nozzle

2203/0766 . . . Rinsing, e.g. after cleaning or polishing a conductive pattern

2203/0769 . . . Dissolving insulating materials, e.g. coatings, not used for developing resist after exposure

2203/0773 . . . Dissolving the filler without dissolving the matrix material; Dissolving the matrix material without dissolving the filler

2203/0776 . . . Uses of liquids not otherwise provided for in H05K 2203/0759 - H05K 2203/0773

2203/0779 . . . characterised by the specific liquids involved

2203/0783 . . . Using solvent, e.g. for cleaning; Regulating solvent content of pastes or coatings for adjusting the viscosity

2203/0786 . . . Using an aqueous solution, e.g. for cleaning or during drilling of holes

2203/0789 . . . Aqueous acid solution, e.g. for cleaning or etching

2203/0793 . . . Aqueous alkaline solution, e.g. for cleaning or etching

2203/0796 . . . Oxidant in aqueous solution, e.g. permanganate

2203/08 . . . Treatments involving gases

2203/081 . . . Blowing of gas, e.g. for cooling or for providing heat during solder reflowing

2203/082 . . . Suction, e.g. for holding solder balls or components

2203/083 . . . Evaporation or sublimation of a compound, e.g. gas bubble generating agent

2203/085 . . . Using vacuum or low pressure

2203/086 . . . Using an inert gas

2203/087 . . . Using a reactive gas

2203/088 . . . Using a vapour or mist, e.g. cleaning using water vapor

2203/09 . . . Treatments involving charged particles

2203/092 . . . Particle beam, e.g. using an electron beam or an ion beam

2203/095 . . . Plasma, e.g. for treating a substrate to improve adhesion with a conductor or for cleaning holes

2203/097 . . . Corona discharge

2203/10 . . . Using electric, magnetic and electromagnetic fields; Using laser light

2203/101 . . . Using electrical induction, e.g. for heating during soldering

2203/102 . . . Using microwaves, e.g. for curing ink patterns or adhesive

2203/104 . . . Using magnetic force, e.g. to align particles or for a temporary connection during processing

2203/105 . . . Using an electrical field; Special methods of applying an electric potential (electroplating H05K 2203/0723)

2203/107 . . . Using laser light (shaping a substrate by laser ablation H05K 3/0026)

2203/108 . . . Using a plurality of lasers or laser light with a plurality of wavelengths

2203/11 . . . Treatments characterised by their effect, e.g. heating, cooling, roughening

2203/1105 . . . Heating or thermal processing not related to soldering, firing, curing or laminating, e.g. for shaping the substrate or during finish plating
Techniques; Protective layers

Moulding and encapsulation

Molten metals, e.g. casting thereof, or melting by
Lubricants, e.g. during drilling of holes
Inorganic compounds, e.g. silver salt
Organic non-polymeric compounds, e.g. oil, wax,
Metallo-organic compounds
Aging
State of a material, e.g. annealing for stress-relief,
Thermal treatment leading to a different chemical
Insulating layer
Pressing leads, bumps or a die through an
Underetching
dielectrics; Means for allowing or controlling conductors or etching of conductor under
Underetching, e.g. etching of substrate under
Means for venting or for letting gases escape
Graft-polymerization
Differences in wettability, e.g. hydrophilic or
hydrophobic areas
Means for venting or for letting gases escape
Underetching, e.g. etching of substrate under
conductors or etching of conductor under
dielectrics; Means for allowing or controlling underetching
Pressing leads, bumps or a die through an
insulating layer
Thermal treatment leading to a different chemical
state of a material, e.g. annealing for stress-relief,
aging
Using specific substances
Metallo-organic compounds
Organic non-polymeric compounds, e.g. oil, wax,
thiol (using solvent H05K 2203/0783)
Heterocyclic organic compounds, e.g. azole, furan
Inorganic compounds, e.g. silver salt
Lubricants, e.g. during drilling of holes
Molten metals, e.g. casting thereof, or melting by
heating and excluding molten solder (spraying droplets of molten metal H05K 2203/1344)
Moulding and encapsulation; Deposition
techniques; Protective layers
Moulding and encapsulation
Foil encapsulation, e.g. of mounted
components
Encapsulated encapsulation of mounted
components
Encapsulation comprising more than one layer
Moulding over PCB locally or completely
(spraying non-metallic protective coatings for
encapsulating mounted components H05K 3/284)
Deposition techniques, e.g. coating
Chemical vapour deposition
Spraying small metal particles or droplets of
molten metal
Electrophoretic deposition of insulating material
Powder coating of insulating material
Coating by immersion in coating bath
(applying molten solder H05K 3/3468)
Spraying coating (apparatus for coating printed
circuit boards using liquid non-metallic coating
compositions H05K 3/0091)
Coating by using a liquid wave (solder dip
coating H05K 2203/04)
Protective layers
Temporary protective insulating layer
Temporary protective conductive layer
Covering open PTHs, e.g. by dry film resist or
by metal disc
Related to the order of processing steps
Applying catalyst before applying plating resist
Applying catalyst after applying plating resist
Applying catalyst before etching, e.g. plating
catalyst in holes before etching circuit
Treating holes before another process, e.g.
coating holes before coating the substrate
Treating holes after another process, e.g. coating
holes after coating the substrate (metal used as
mask for etching vias H05K 2203/0554)
Treatment after insertion of lead into hole, e.g.
bending, cutting, caulking or curing of adhesive
but excluding soldering
Applying the circuit pattern before another
process, e.g. before filling of vias with conductive
paste, before making printed resistors
Applying or finishing the circuit pattern after
another process, e.g. after filling of vias with
conductive paste, after making printed resistors
Circuit made after mounting or encapsulation
of the components
Same or similar kind of process performed in
phases, e.g. coarse patterning followed by fine
patterning
Simultaneous treatments, e.g. soldering lead-in-
hole components simultaneously with surface
mounted components
Periodical treatments, e.g. pulse plating of
through-holes
Position of the PCB during processing
Horizontally held PCB
Vertically held PCB
Obliquely held PCB
Temporarily stacked PCBs
Continuous processing, i.e. involving rolls
moving a band-like or solid carrier along a
continuous production path
Rotating or turning the PCB in a continuous
manner
Reversing the PCB
Processing both sides of a PCB by the same
process; Providing a similar arrangement of
components on both sides; Making interlayer
connections from two sides
Treating the backside of the PCB, e.g. for heating
during soldering or providing a liquid coating on
the backside
Using gravitational force; Processing against
the gravity direction; Using centrifugal force
Inspection; Monitoring; Aligning
Using chemical substances, e.g. colored or fluorescent, for facilitating optical or visual inspection

Testing a finished product, e.g. heat cycle testing of solder joints (patterns for electrical inspection or testing H05K 1/0268)

Monitoring a manufacturing process

Stabilizing, e.g. temperature stabilization

Alignment or registration; Control of registration

Using mechanical means for positioning, alignment or registration, e.g. using rod-in-hole alignment

Wrong mounting prevention

Post-manufacturing processes

Adding connections between adjacent pads or conductors, e.g. for modifying or repairing (programmable, customizable or modifiable circuits H05K 1/0286)

Configurations of connections suitable for easy deletion, e.g. modifiable circuits or temporary conductors for electroplating; Processes for deleting connections

Removing, replacing or disconnecting component; Easily removable component (thermal arrangements, e.g. to prevent overheating H05K 1/0201)

Demolishing, e.g. recycling, reverse engineering, destroying for security purposes; Using biodegradable materials

Details of processes not otherwise provided for in H05K 2203/01 - H05K 2203/17

Bending a rigid substrate; Breaking rigid substrates by bending (rigid circuit boards or rigid supports locally made bendable H05K 1/0278)

Protecting a component during manufacturing

Lifting the component during or after mounting; Increasing the gap between component and PCB

Sacrificial means, e.g. for temporarily filling a space for making a via or a cavity or for making rigid-flexible PCBs

Dummy groups for the purpose of scheme testing, logistics of documents or the like

999/00 dummy group

WARNING

This group and its subgroups are not real classification places. They are used only for the purpose of scheme testing, logistics of documents or the like.

999/99 dummy group